

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE


Application Serial No. 09/148,723  
Filing Date September 3, 1998  
Inventor Warren M. Farnworth et al.  
Assignee Micron Technology, Inc.  
Group Art Unit 3729  
Examiner A. Tugbang  
Attorney's Docket No. MI22-981  
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate (As Amended)

Assistant Commissioner for Patents  
Washington, D.C. 20231

ASSOCIATE POWER OF ATTORNEY

Please recognize Frederick M. Fliegel, Reg. No. 36,138; Bernard Berman, Reg. No. 37,279; D. Brent Kenady, Reg. No. 40,045; and James E. Lake, Reg. No. 44,854; whose post office address is 601 W. First Avenue, Suite 1300, Spokane, Washington 99201-3828, as associate attorneys or agents in the above-entitled application.

Date: 3-9-00

  
Mark S. Matkin  
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